

## 1. General description

Planar passivated high commutation three quadrant triac in a SOT186A "full pack" plastic package intended for use in circuits where high static and dynamic  $dV/dt$  and high  $dI/dt$  can occur. This "series CT" triac will commute the full RMS current at the maximum rated junction temperature ( $T_{j(max)} = 150\text{ °C}$ ) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

## 2. Features and benefits

- 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High junction operating temperature capability ( $T_{j(max)} = 150\text{ °C}$ )
- High immunity to false turn-on by  $dV/dt$
- High voltage capability
- Isolated mounting base package
- Less sensitive gate for very high noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

## 3. Applications

- Applications subject to high temperature ( $T_{j(max)} = 150\text{ °C}$ )
- Electronic thermostats
- High power motor controls e.g. washing machines and vacuum cleaners
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids
- Refrigeration and air conditioning compressor

## 4. Quick reference data

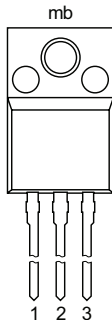
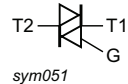
Table 1. Quick reference data

| Symbol                         | Parameter                            | Conditions   | Values | Unit |
|--------------------------------|--------------------------------------|--|--------|------|
| <b>Absolute maximum rating</b> |                                      |  |        |      |
| $V_{DRM}$                      | repetitive peak off-state voltage    |  | 800    | V    |
| $I_{T(RMS)}$                   | RMS on-state current                 | full sine wave; $T_h \leq 67\text{ °C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>    | 16     | A    |
| $I_{TSM}$                      | non-repetitive peak on-state current | full sine wave; $t_p = 20\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$ ;<br><a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> | 140    | A    |
|                                |                                      | full sine wave; $t_p = 16.7\text{ ms}$ ; $T_{j(init)} = 25\text{ °C}$  | 150    | A    |
| $T_j$                          | junction temperature                 |  | 150    | °C   |

| Symbol                         | Parameter                             | Conditions   | Min | Typ | Max | Unit |
|--------------------------------|---------------------------------------|--|-----|-----|-----|------|
| <b>Static characteristics</b>  |                                       |  |     |     |     |      |
| I <sub>GT</sub>                | gate trigger current                  | V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+<br>T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>  | 2   | -   | 35  | mA   |
|                                |                                       | V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-<br>T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>  | 2   | -   | 35  | mA   |
|                                |                                       | V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-<br>T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>  | 2   | -   | 35  | mA   |
| I <sub>H</sub>                 | holding current                       | V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 9</a>  | -   | -   | 35  | mA   |
| V <sub>T</sub>                 | on-state voltage                      | I <sub>T</sub> = 18 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 10</a>   | -   | 1.3 | 1.5 | V    |
| <b>Dynamic characteristics</b> |                                       |  |     |     |     |      |
| dV <sub>D</sub> /dt            | rate of rise of off-state voltage     | V <sub>DM</sub> = 536 V; T <sub>j</sub> = 125 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit                | 500 | -   | -   | V/μs |
|                                |                                       | V <sub>DM</sub> = 536 V; T <sub>j</sub> = 150 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit                | 200 | -   | -   | V/μs |
| dI <sub>com</sub> /dt          | rate of change of commutating current | V <sub>D</sub> = 400 V; T <sub>j</sub> = 150 °C; I <sub>T(RMS)</sub> = 16 A; dV <sub>com</sub> /dt = 20 V/μs; gate open circuit; snubberless condition | 8   | -   | -   | A/ms |

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description             | Simplified outline   | Graphic symbol  |
|-----|--------|-------------------------|--|---|
| 1   | T1     | main terminal 1         |  |  |
| 2   | T2     | main terminal 2         |  |   |
| 3   | G      | gate                    |  |   |
| mb  | n.c.   | mounting base; isolated |  |   |

## 6. Ordering information

Table 3. Ordering information

| Type number   | Package |   |         |
|---------------|---------|---|---------|
|               | Name    | Description   | Version |
| BTA316X-800CT | TO-220F | Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 'full pack' | SOT186A |

## 7. Marking

Table 4. Marking codes

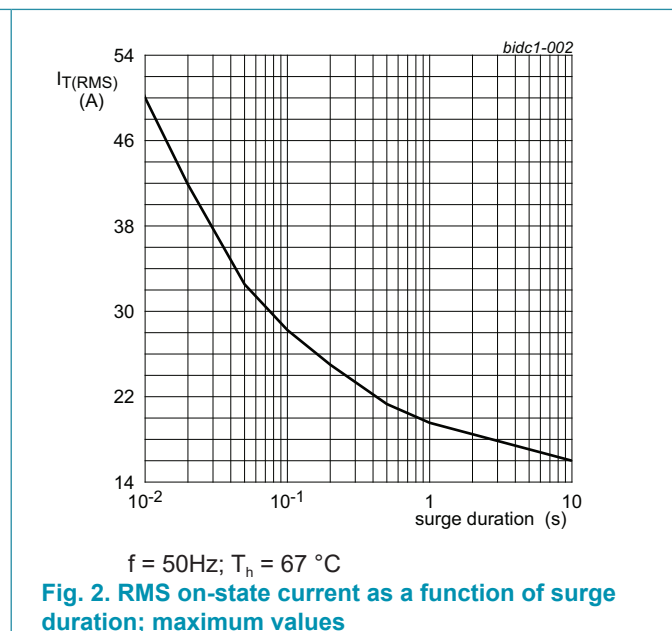
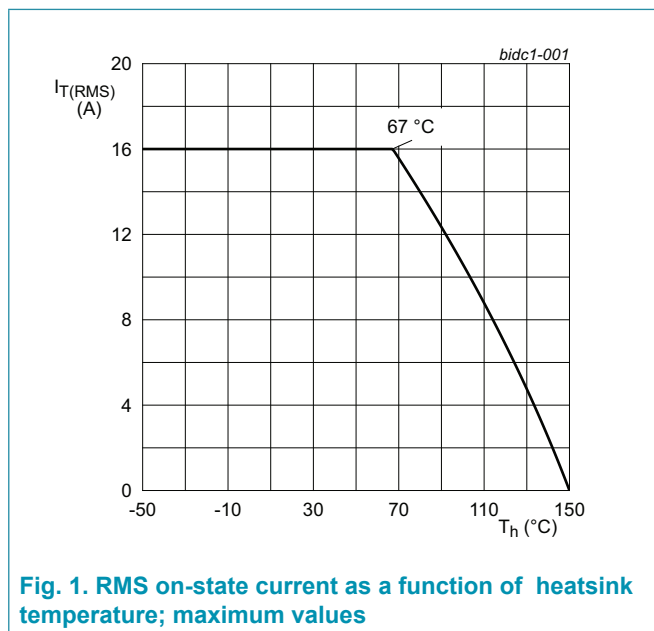
| Type number   | Marking codes |
|---------------|---------------|
| BTA316X-800CT | BTA316X-800CT |

## 8. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol       | Parameter                            | Conditions  | Values     | Unit                   |
|--------------|--------------------------------------|---|------------|------------------------|
| $V_{DRM}$    | repetitive peak off-state voltage    |   | 800        | V                      |
| $I_{T(RMS)}$ | RMS on-state current                 | full sine wave; $T_h \leq 67\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>           | 16         | A                      |
| $I_{TSM}$    | non-repetitive peak on-state current | full sine wave; $t_p = 20\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ;<br><a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a> | 140        | A                      |
|              |                                      | full sine wave; $t_p = 16.7\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$  | 150        | A                      |
| $I^2t$       | $I^2t$ for fusing                    | $t_p = 10\text{ms}$ ; sine wave   | 98         | $\text{A}^2\text{s}$   |
| $dI_T/dt$    | rate of rise of on-state current     | $I_G = 70\text{mA}$   | 100        | $\text{A}/\mu\text{s}$ |
| $I_{GM}$     | peak gate current                    |   | 2          | A                      |
| $P_{GM}$     | peak gate power                      |   | 5          | W                      |
| $P_{G(AV)}$  | average gate power                   | over any 20 ms period   | 0.5        | W                      |
| $T_{stg}$    | storage temperature                  |   | -40 to 150 | $^\circ\text{C}$       |
| $T_j$        | junction temperature                 |   | 150        | $^\circ\text{C}$       |



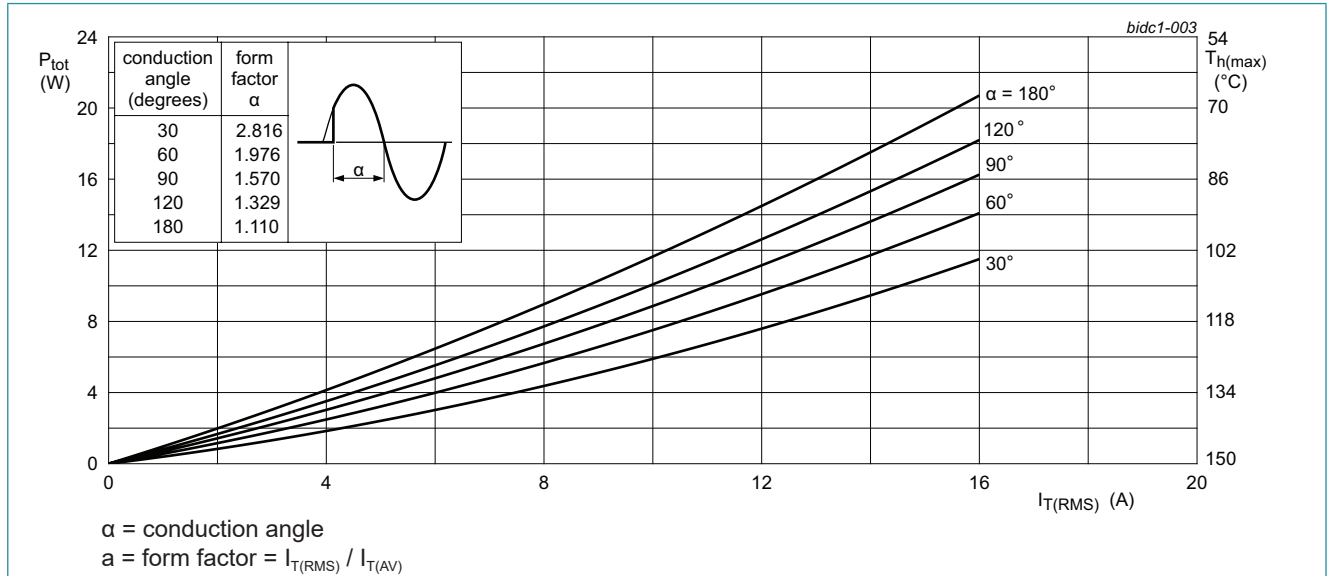


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

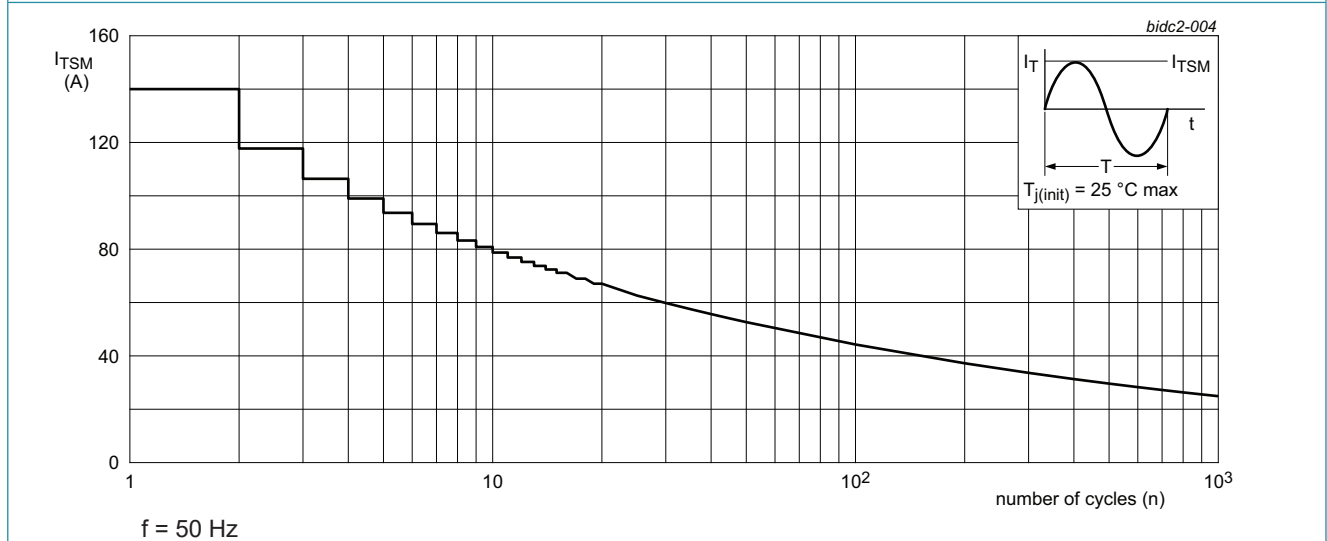


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

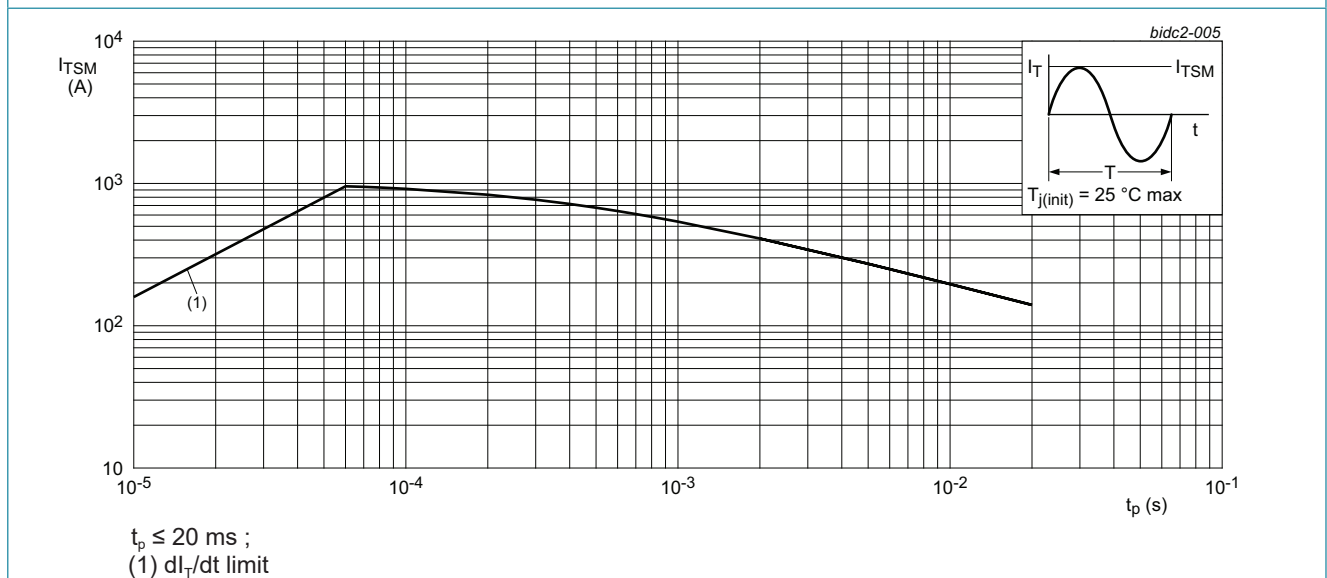


Fig. 5. Total power dissipation as a function of RMS on-state current; maximum values

## 9. Thermal characteristics

Table 5. Thermal characteristics

| Symbol        | Parameter  | Conditions                                       | Min | Typ | Max | Unit |
|---------------|--|--|-----|-----|-----|------|
| $R_{th(j-h)}$ | thermal resistance from junction to heatsink         | with heatsink compound; <a href="#">Fig. 6</a>   | -   | -   | 4   | K/W  |
|               |  | without heatsinkcompound; <a href="#">Fig. 6</a> | -   | -   | 5.5 | K/W  |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient free air | in free air                                      | -   | 55  | -   | K/W  |

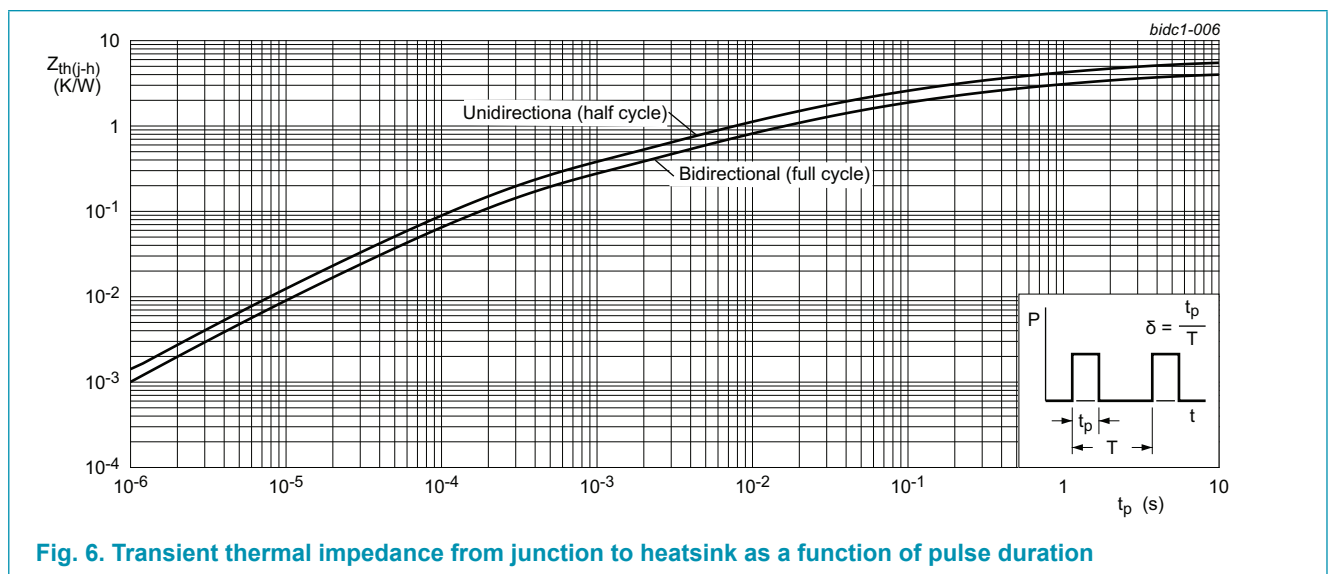


Fig. 6. Transient thermal impedance from junction to heatsink as a function of pulse duration

## 10. Isolation characteristics

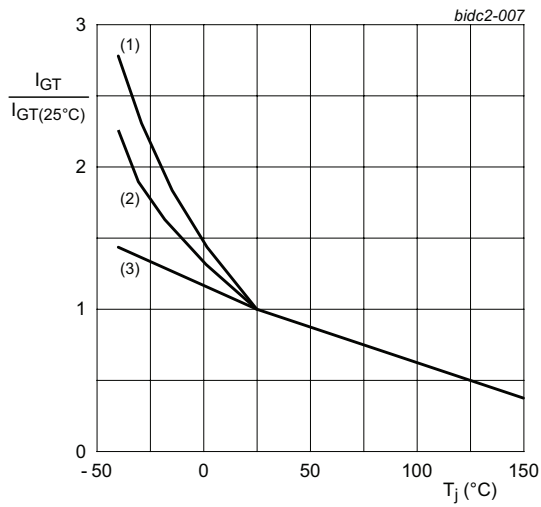
Table 6. Isolation characteristics

| Symbol          | Parameter             | Conditions  | Min | Typ | Max  | Unit |
|-----------------|-----------------------|---|-----|-----|------|------|
| $V_{isol(RMS)}$ | RMS isolation voltage | 50 Hz $\leq$ f $\leq$ 60 Hz; RH $\leq$ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free | -   | -   | 2500 | V    |
| $C_{isol}$      | isolation capacitance | from cathode to external heatsink   | -   | 10  | -    | PF   |

## 11. Characteristics

Table 7. Characteristics

| Symbol                         | Parameter                             | Conditions  | Min  | Typ | Max | Unit             |
|--------------------------------|---------------------------------------|---|------|-----|-----|------------------|
| <b>Static characteristics</b>  |                                       |   |      |     |     |                  |
| $I_{GT}$                       | gate trigger current                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+;<br>$T_J = 25\text{ °C}$ ; <a href="#">Fig. 7</a>   | 2    | -   | 35  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-;<br>$T_J = 25\text{ °C}$ ; <a href="#">Fig. 7</a>   | 2    | -   | 35  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_J = 25\text{ °C}$ ; <a href="#">Fig. 7</a>   | 2    | -   | 35  | mA               |
| $I_L$                          | latching current                      | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+;<br>$T_J = 25\text{ °C}$ ; <a href="#">Fig. 8</a>   | -    | -   | 50  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G-;<br>$T_J = 25\text{ °C}$ ; <a href="#">Fig. 8</a>   | -    | -   | 60  | mA               |
|                                |                                       | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2- G-;<br>$T_J = 25\text{ °C}$ ; <a href="#">Fig. 8</a>   | -    | -   | 50  | mA               |
| $I_H$                          | holding current                       | $V_D = 12\text{ V}$ ; $T_J = 25\text{ °C}$ ; <a href="#">Fig. 9</a>   | -    | -   | 35  | mA               |
| $V_T$                          | on-state voltage                      | $I_T = 18\text{ A}$ ; $T_J = 25\text{ °C}$ ; <a href="#">Fig. 10</a>  | -    | 1.3 | 1.5 | V                |
| $V_{GT}$                       | gate trigger voltage                  | $V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_J = 25\text{ °C}$ ;<br><a href="#">Fig. 11</a>  | -    | 0.8 | 1   | V                |
|                                |                                       | $V_D = 400\text{ V}$ ; $I_T = 0.1\text{ A}$ ; $T_J = 150\text{ °C}$ ;<br><a href="#">Fig. 11</a>  | 0.25 | 0.4 | -   | V                |
| $I_D$                          | off-state current                     | $V_D = 800\text{ V}$ ; $T_J = 25\text{ °C}$   | -    | -   | 10  | $\mu\text{A}$    |
|                                |                                       | $V_D = 800\text{ V}$ ; $T_J = 150\text{ °C}$  | -    | -   | 2   | mA               |
| <b>Dynamic characteristics</b> |                                       |   |      |     |     |                  |
| $dV_D/dt$                      | rate of rise of off-state voltage     | $V_{DM} = 536\text{ V}$ ; $T_J = 125\text{ °C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit                                       | 500  | -   | -   | V/ $\mu\text{s}$ |
|                                |                                       | $V_{DM} = 536\text{ V}$ ; $T_J = 150\text{ °C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit                                       | 200  | -   | -   | V/ $\mu\text{s}$ |
| $di_{com}/dt$                  | rate of change of commutating current | $V_D = 400\text{ V}$ ; $T_J = 150\text{ °C}$ ; $I_{T(RMS)} = 16\text{ A}$ ;<br>$dV_{com}/dt = 20\text{ V}/\mu\text{s}$ ; gate open circuit; snubberless condition | 8    | -   | -   | A/ms             |



- (1) T2- G-
- (2) T2+ G-
- (3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of junction temperature

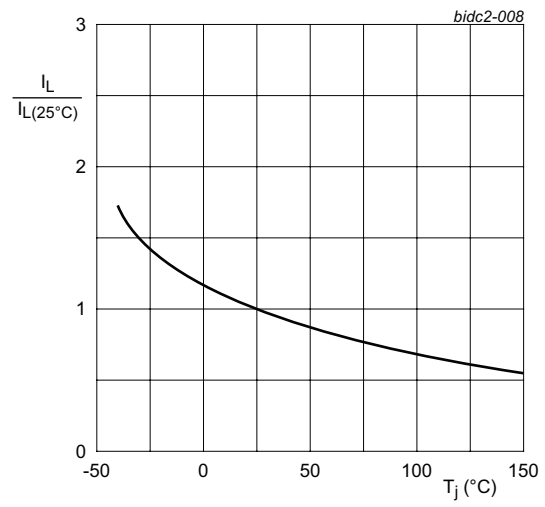


Fig. 8. Normalized latching current as a function of junction temperature

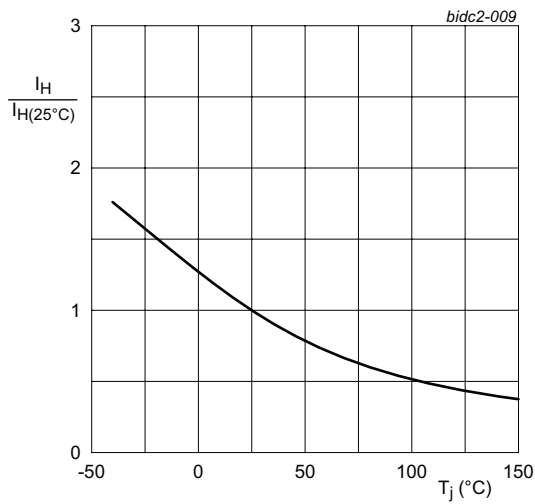
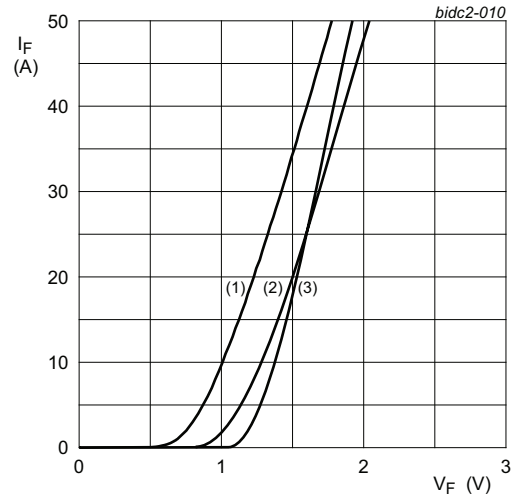


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.053 \text{ V}; R_s = 0.0216 \Omega$

- (1)  $T_j = 150^\circ\text{C}$ ; typical values
- (2)  $T_j = 150^\circ\text{C}$ ; maximum values
- (3)  $T_j = 25^\circ\text{C}$ ; maximum values

Fig. 10. On-state current as a function of on-state voltage

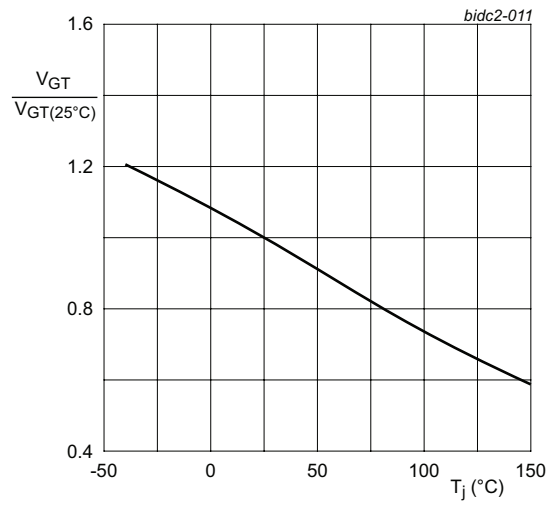


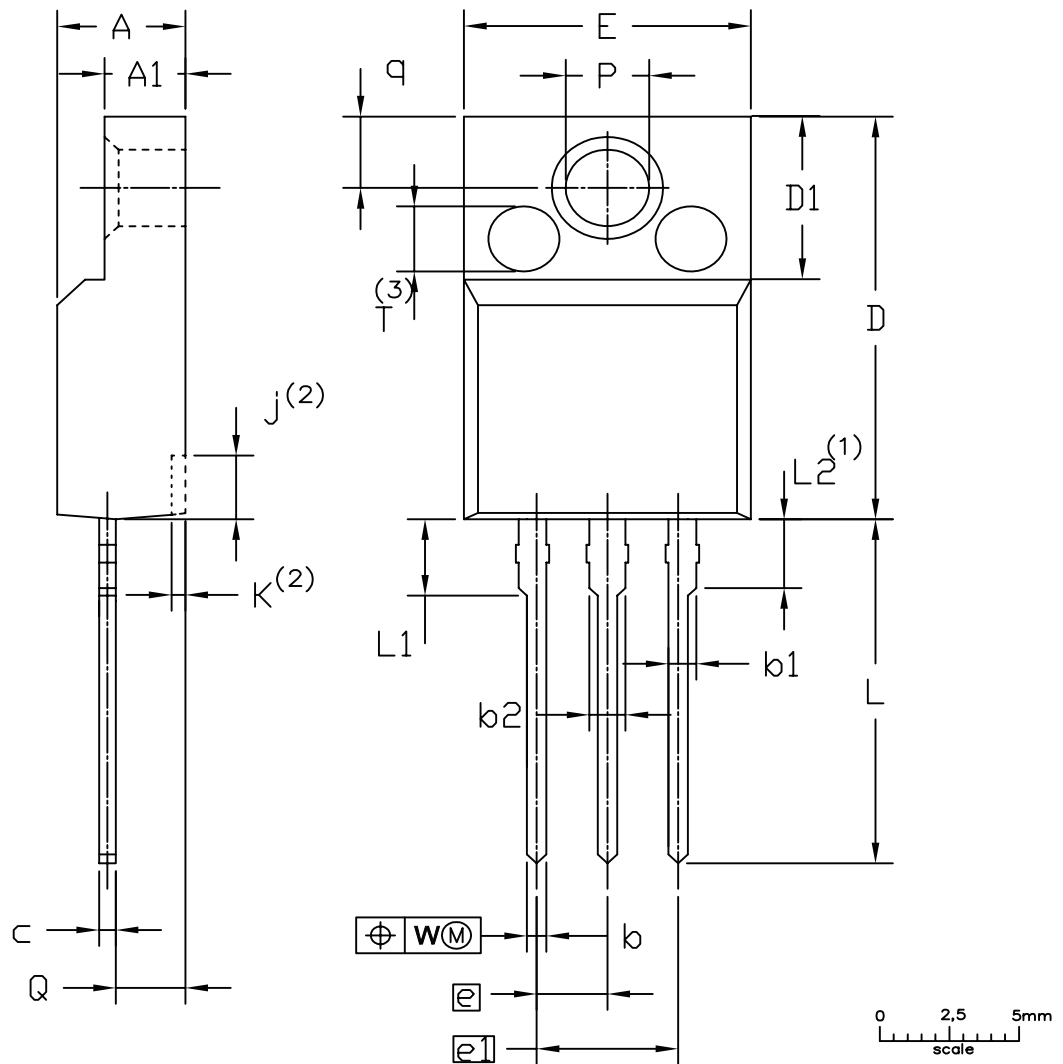
Fig. 11. Normalized gate trigger voltage as a function of junction temperature



### 12. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"

SOT186A



| UNIT | A   | A <sub>1</sub> | b   | b <sub>1</sub> | b <sub>2</sub> | c   | D    | D <sub>1</sub> | E    | e    | e <sub>1</sub> | j <sup>(2)</sup> | k <sup>(2)</sup> | L    | L <sub>1</sub> | L <sub>2</sub> <sup>(1)</sup><br>max. | P   | Q   | q   | W   | T <sup>(3)</sup> |
|------|-----|----------------|-----|----------------|----------------|-----|------|----------------|------|------|----------------|------------------|------------------|------|----------------|---------------------------------------|-----|-----|-----|-----|------------------|
| mm   | 4.6 | 2.9            | 0.9 | 1.1            | 1.4            | 0.7 | 15.8 | 6.5            | 10.3 | 2.54 | 5.08           | 2.7              | 0.6              | 14.4 | 3.30           | 3                                     | 3.2 | 2.6 | 3.0 | 0.4 | 2.5              |
|      | 4.0 | 2.5            | 0.7 | 0.9            | 1.0            | 0.4 | 15.2 | 6.3            | 9.7  |      |                | 1.7              | 0.4              | 13.5 | 2.79           |                                       | 3.0 | 2.3 | 2.6 |     |                  |

Notes

- Terminal dimensions within this zone are uncontrolled
- Dot lines area designs may vary
- Eject pin mark is for reference only

| OUTLINE<br>VERSION | REFERENCES |                |       | EUROPEAN<br>PROJECTION | ISSUE DATE |
|--------------------|------------|----------------|-------|------------------------|------------|
|                    | IEC        | JEDEC          | JEITA |                        |            |
| SOT186A            |            | 3 LEADS TO220F |       |                        | 2013-11-14 |

## 13. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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Date of release: 12 September 2018

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